Specification for Production

Applicant / Manufacturer Hardware	Panasonic Electronic Devices Europe GmbH Zeppelinstrasse 19 21337 Lüneburg Germany
Applicant / Manufacturer Software	Please refer to chapter 22 / 22.1 Information regarding Software Versions
Software Version	Please refer to chapter 22 / 22.1 Information regarding Software Versions

By purchase of any of products described in this document the customer accepts the document's validity and declares their agreement and understanding of its contents and recommendations. Panasonic reserves the right to make changes as required without notification.

TABLE OF CONTENTS

1. Scope of this Document 4
2. Difference PAN1720 / PAN1721 4
3. Key Features 4
4. Bluetooth Low Energy 5
5. Applications for the Module 5
6. Description for the Module 5
7. Detailed Description 6
   7.1. PAN172x Terminal Layout 6
8. Bluetooth Features 8
9. Block Diagram 8
10. Test Conditions 9
11. General Device Requirements and Operation 9
   11.1. Absolute Maximum Ratings 9
   11.2. Recommended Operating Conditions 9
   11.3. Current Consumption 10
12. Bluetooth RF Performance 11
   12.1. Bluetooth Characteristics 11
13. Soldering Temperature-Time Profile (for reflow soldering) 12
   13.1. For lead solder 12
   13.2. For leadfree solder 12
14. Module Dimension 13
15. PAN172x FootPrint of the Module 14
16. Case Marking 15
   16.1. Example for Marking 15
   16.2. Marking Definition 15
17. Mechanical Requirements 16
18. Development of Applications 16
19. Reliability Tests 16
20. Cautions 16
   20.1. Design Notes 16
   20.2. Installation Notes 17
   20.3. Usage Conditions Notes 17
   20.4. Storage Notes 18
   20.5. Safety Cautions 18
   20.6. Other cautions 18
21. Packaging 20
   21.1. Tape Dimension 20
   21.2. Packing in Tape 20
   21.3. Component direction 21

21.4. Reel Dimension 21
21.5. Label for Package 22
21.6. Total Package 22
22. Ordering Information 23
22.1. Information regarding Software Versions 23
23. RoHS Declaration 24
24. Data Sheet Status 25
25. History for this Document 25
26. Related Documents 25
27. General Information 26
28. Regulatory Information 26
28.1. FCC Notice 26
28.2. Caution 26
28.3. Labeling Requirements 27
28.4. Antenna Warning 27
28.5. Approved Antenna List 27
28.6. RF Exposure PAN172x 27
29. Industry Canada Certification 28
29.1. IC Notice 28
29.2. Labeling Requirements 28
30. European R&TTE Declaration of Conformity 28
31. Life Support Policy 29

1. SCOPE OF THIS DOCUMENT

This product specification applies to Panasonic's, Class 2, Bluetooth®[1] low energy single mode module, series number: PAN1720 (CC2540 from Texas Instruments) and PAN1721 (CC2541 from Texas Instruments). Different memory versions of the PAN172x are available.

2. DIFFERENCE PAN1720 / PAN1721

Difference PAN1720 and PAN1721 is the IC from Texas Instruments only.
Both are refered to PAN172x in this document.

The CC2541 is pin-compatible with the CC2540 in the 6-mm × 6-mm QFN40 package, if the USB is not used on the CC2540 and the I2C/extra I/O is not used on the CC2541. Compared to the CC2540, the CC2541 provides lower RF current consumption. The CC2541 does not have the USB interface of the CC2540, and provides lower maximum output power in TX mode. The CC2541 also adds a HW I2C interface.

More detailed differences regarding the IC, which have an impact on the module can be seen in the datasheets from Texas Instruments.

CC2540 from Texas Instruments

CC2541 from Texas Instruments

3. KEY FEATURES

- Bluetooth Low Energy Single Mode 4.0
- Surface mount type 15.6 x 8.7 x 1.8 mm³
- Up to 4.0 dBm Tx power (typical) with transmit power control
- High sensitivity (-94 dBm typ.)
- Texas Instrument's CC2540 Single Chip BLE Solution inside
- High performance low power 8051 Microcontroller core
- No external components needed
- Fast Connection Setup
- Internal crystal oscillator (26MHz)
- Internal 32khz crystal oscillator for Sleep Timer
- Two powerful USARTs
- USB direct support
- Powerful five channel DMA
- Latest Profiles included e.g. Battery Monitor and Temperature sensor
- Integrated shielding to resist EMI
- Manufactured in conformance with RoHS

[1] Bluetooth is a registered trademark of the Bluetooth Special Interest Group.

4. BLUETOOTH LOW ENERGY

Bluetooth Low Energy (BLE), part of Bluetooth Ver. 4.0, specifies two types of implementation: Single mode and dual mode. Single mode chips implement the low energy specification and consume just a fraction of the power of classic Bluetooth, allowing the short-range wireless standard to extend to coin cell battery applications for the first time. Dual mode chips combine low energy with the power of classic Bluetooth and are likely to become a de facto feature in almost all new Bluetooth enabled cellular phones and computers.

Single mode Bluetooth 4.0 Low Energy is not backwards compatible with previous Bluetooth standards. Dual mode Bluetooth 4.0 Low Energy is backwards compatible but is not practical for low power devices but targeted to gateway products

5. APPLICATIONS FOR THE MODULE

All Embedded Wireless Applications

- Access Points
- Industrial Control
- Medical
- Scanners
- Wireless Sensors
- Low Power
- Proximity
- Smart Phone
- Access Points
- Temperature
- Wellness
- Sports

6. DESCRIPTION FOR THE MODULE

The PAN172x is a short-range Class 2 BLE single mode module for implementing Bluetooth functionality into various electronic devices. A block diagram can be found in chapter 9.

The PAN172x is a cost-effective, low-power, true system-on-chip (SoC) for Bluetooth low energy applications. It enables robust BLE master or slave nodes to be built with very low total bill-of-material costs. The PAN172x combines an excellent RF transceiver with an industry-standard enhanced 8051 MCU, in-system programmable flash memory, 8-KB RAM, and many other powerful supporting features and peripherals. The PAN172x is suitable for systems where very low power consumption is required. Very low-power sleep modes are available. Short transition times between operating modes further enable low power consumption.

Combined with the Bluetooth low energy protocol stack from Texas Instruments, the PAN172x forms the market's most flexible and cost-effective single-mode Bluetooth low energy solution.

Additional embedded software solutions and profiles are available from other Panasonic software partners. Refer to 0PAN172xETU Design-Guide.

Please contact your local sales office for further details on additional options and services:

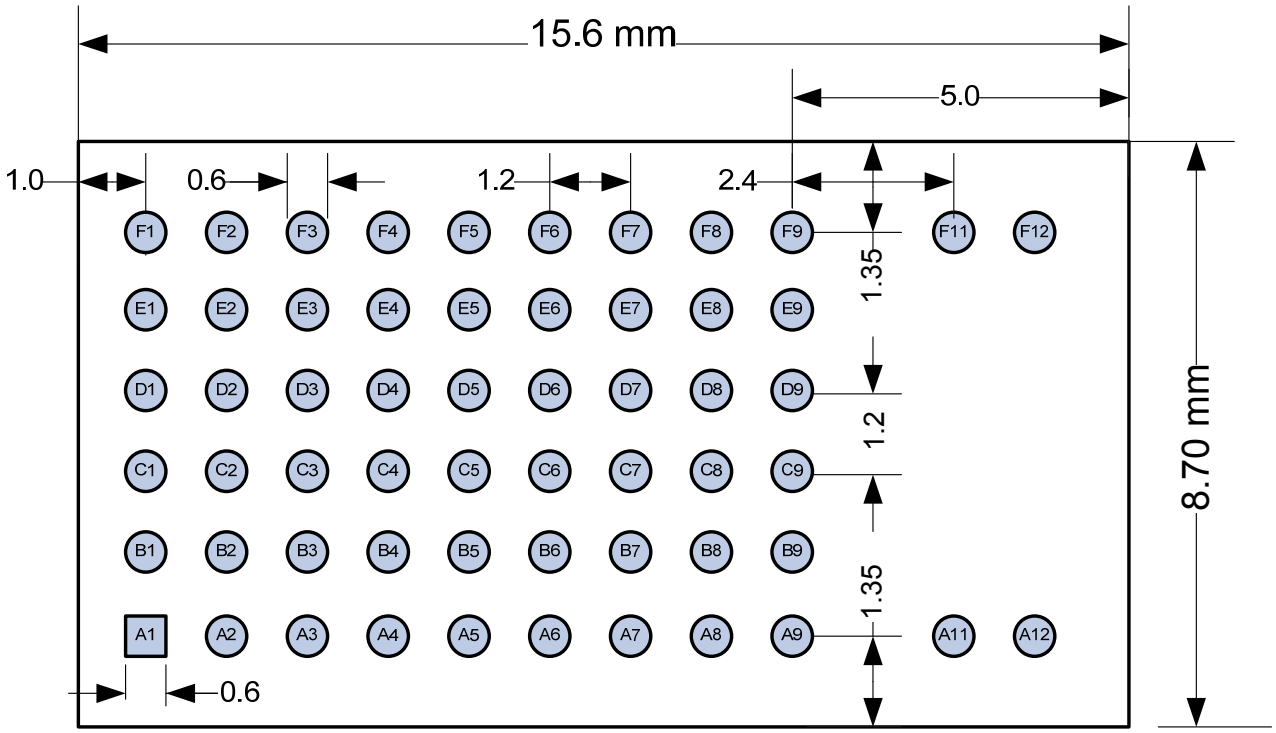
www.panasonic.com/rfmodules for the US,
http://industrial.panasonic.com/eu/i/29606/wireless_modules/wireless_modules.html for EU

or write an e-mail to wireless@eu.panasonic.com.

7. DETAILED DESCRIPTION

7.1. PAN172X TERMINAL LAYOUT

Top view, Application PCB

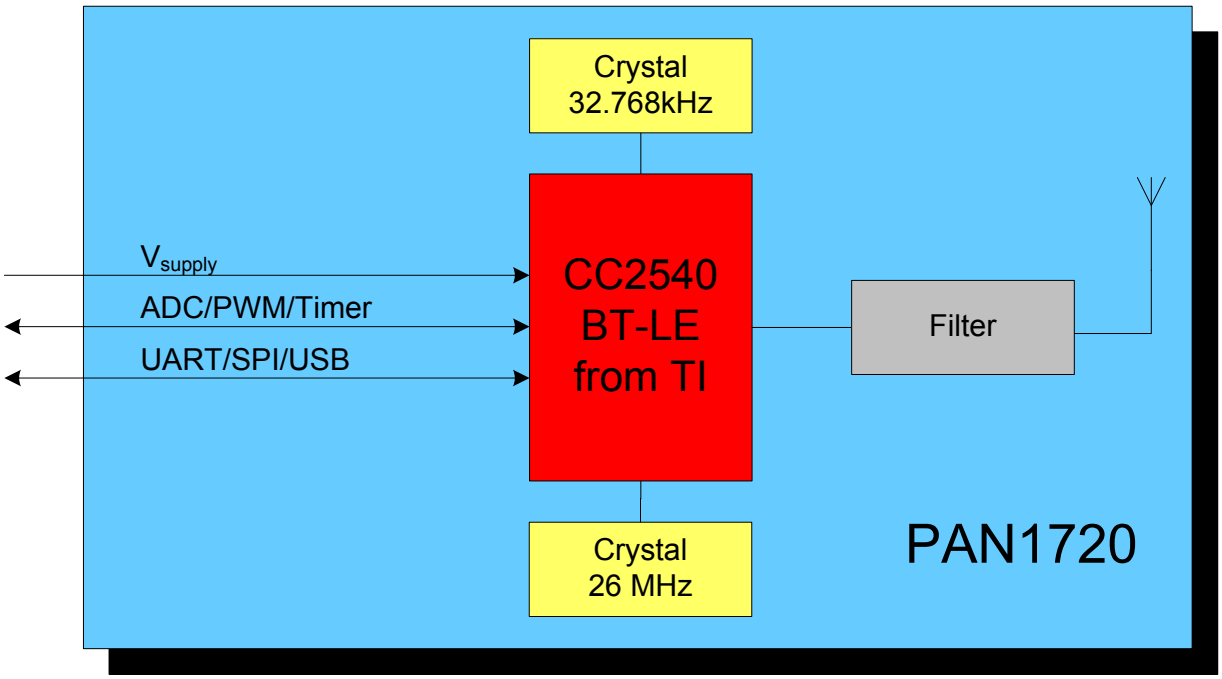


No	Pin Name	Pin Type	Description
A1	GND	Ground Pin	Connect to Ground
A2	P1.0	Digital I/O	Port 1.0 – 20mA drive capability
A3	Reset	Digital Input	Reset, active-low
A4	VCC	Power	2V – 3.6V analog/digital power supply connection
A5	VCC	Power	2V – 3.6V analog/digital power supply connection
A6	VCC	Power	2V – 3.6V analog/digital power supply connection
A7	GND	Ground Pin	Connect to Ground
A8	NC		Not Connected
A9	GND	Ground Pin	Connect to Ground
A11	GND	Ground Pin	Connect to Ground
A12	GND	Ground Pin	Connect to Ground
B1	P1.3	Digital I/O	Port 1.3
B2	P1.2	Digital I/O	Port 1.2
B3	P1.1	Digital I/O	Port 1.1 – 20mA drive capability
B4	P0.6	Digital I/O	Port 0.6
B5	NC		Not Connected
B6	P0.1	Digital I/O	Port 0.1
B7	P0.0	Digital I/O	Port 0.0
B8	NC		Not Connected
B9	NC		Not Connected
C1	NC		Not Connected
C2	P1.4	Digital I/O	Port 1.4 / BR-SW UART CTS
C3	P1.5	Digital I/O	Port 1.5 / BR-SW UART RTS
C4	P0.7	Digital I/O	Port 0.7
C5	NC		Not Connected
C6	NC		Not Connected
C7	NC		Not Connected
C8	GND	Ground Pin	Connect to Ground
C9	GND	Ground Pin	Connect to Ground
D1	DVDD_USB	Power (digital)	2V – 3.6V digital power supply connection
D2	USB_N	Digital I/O	USB N / PAN1721 I2C SDA // Leave floating if not used.
D3	USB_P	Digital I/O	USB P / PAN1721 I2C SCL // Leave floating if not used.
D4	NC		Not Connected
D5	NC		Not Connected
D6	NC		Not Connected
D7	GND	Ground Pin	Connect to Ground
D8	GND	Ground Pin	Connect to Ground
D9	NC		Not Connected
E1	P2.1/DD	Digital I/O	Port 2.1 / Programming Interface DD
E2	P2.2/DC	Digital I/O	Port 2.2 / Programming Interface DC
E3	DGND_USB	Ground Pin	Connect to Ground
E4	NC		Not Connected
E5	NC		Not Connected
E6	P0.2/RX/MISO	Digital I/O	Port 0.2 / TI-SW UART RX / SPI MISO
E7	NC		Not Connected
E8	GND	Ground Pin	Connect to Ground
E9	GND	Ground Pin	Connect to Ground
F1	GND	Ground Pin	Connect to Ground
F2	P1.6	Digital I/O	Port 1.6 / BR-SW UART TX
F3	P1.7	Digital I/O	Port 1.7 / BR-SW UART RX
F4	P2.0	Digital I/O	Port 2.0
F5	P0.4/CTS/CS	Digital I/O	Port 0.4 / TI-SW UART CTS / SPI CS
F6	NC		Not Connected
F7	P0.3/TX/MOSI	Digital I/O	Port 0.3 / TI-SW UART TX /SPI MOSI
F8	P0.5/RTS/CLK	Digital I/O	Port 0.5 / TI-SW UART RTS /SPI CLK
F9	GND	Ground Pin	Connect to Ground
F11	GND	Ground Pin	Connect to Ground
F12	GND	Ground Pin	Connect to Ground

8. BLUETOOTH FEATURES

- Bluetooth 4.0 single mode low energy technology.
- Class 2 TX power w/o external PA, improving link robustness.
- Excellent link budget (up to 96 dB), enabling long-range applications.
- Accurate digital received signal-strength indicator (RSSI)
- Integrates the new low power profiles and services
- Embedded BT-Stack available

9. BLOCK DIAGRAM



Block Diagram of PAN1721 is similar, but has I2C interface instead of USB.

Please refer to chapter 2.

10. TEST CONDITIONS

Measurements shall be made under operating free-air temperature range unless otherwise specified.

Temperature	25 ± 10°C
Humidity	40 to 85%RH
Supply Voltage	3.3V

11. GENERAL DEVICE REQUIREMENTS AND OPERATION

All specifications are over temperature and process, unless indicated otherwise.

11.1. ABSOLUTE MAXIMUM RATINGS

No	See [2]		Value	Unit
Ratings Over Operating Free-Air Temperature Range				
1	Supply voltage	All supply pins must have the same voltage	–0.3 to 3.9	V
2	Voltage on any digital pin		–0.3 to VDD+0.3 <3,9	V
3	Operating ambient temperature range		–40 to 85	°C
4	Storage temperature range		–40 to 125	°C
5	Bluetooth RF inputs		10	dBm
6	ESD: All pads, according to human-body model, JEDEC STD 22, method A114 According to charged-device model, JEDEC STD 22, method C101		 1000 500	V

11.2. RECOMMENDED OPERATING CONDITIONS

No	Rating	Min	Max	Unit
1	Power supply voltage	2	3.6	V
2	Maximum ambient operating temperature	-40	85	°C

[2] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

11.3. CURRENT CONSUMPTION

The current consumption is dependant on the user scenario and the setup and timing in the low power modes. The total power consumption can be optimized by adjusting the scan windows and intervals.

Please refer for the different power modes to the chapter "Electrical Characteristics" in Semiconductor Datasheet 0 for the latest information. As indication below are typical values from CC2540 datasheet.

ELECTRICAL CHARACTERISTICS

Measured on Texas Instruments CC2540 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{core}	Core current consumption	Power mode 1. Digital regulator on; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, BOD and sleep timer active; RAM and register retention		235		µA
		Power mode 2. Digital regulator off; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, and sleep timer active; RAM and register retention		0.9		
		Power mode 3. Digital regulator off; no clocks; POR active; RAM and register retention		0.4		
		Low MCU activity: 32-MHz XOSC running. No radio or peripherals. No flash access, no RAM access.		6.7		mA
I_{peri}	Peripheral current consumption (Adds to core current I_{core} for each peripheral unit activated)	Timer 1. Timer running, 32-MHz XOSC used		90		µA
		Timer 2. Timer running, 32-MHz XOSC used		90		µA
		Timer 3. Timer running, 32-MHz XOSC used		60		µA
		Timer 4. Timer running, 32-MHz XOSC used		70		µA
		Sleep timer, including 32.753-kHz RCOSC		0.6		µA
		ADC, when converting		1.2		mA

GENERAL CHARACTERISTICS

Measured on Texas Instruments CC2540 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
WAKE-UP AND TIMING					
Power mode 1 → Active	Digital regulator on, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of 16-MHz RCOSC		4		µs
Power mode 2 or 3 → Active	Digital regulator off, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of regulator and 16-MHz RCOSC		120		µs
Active → TX or RX	Crystal ESR = 16 Ω. Initially running on 16-MHz RCOSC, with 32-MHz XOSC OFF		410		µs
	With 32-MHz XOSC initially on		160		µs
RX/TX turnaround			150		µs
RADIO PART					
RF frequency range	Programmable in 2-MHz steps	2402		2480	MHz
Data rate and modulation format	1 Mbps, GFSK, 250 kHz deviation				

12. BLUETOOTH RF PERFORMANCE

12.1. BLUETOOTH CHARACTERISTICS

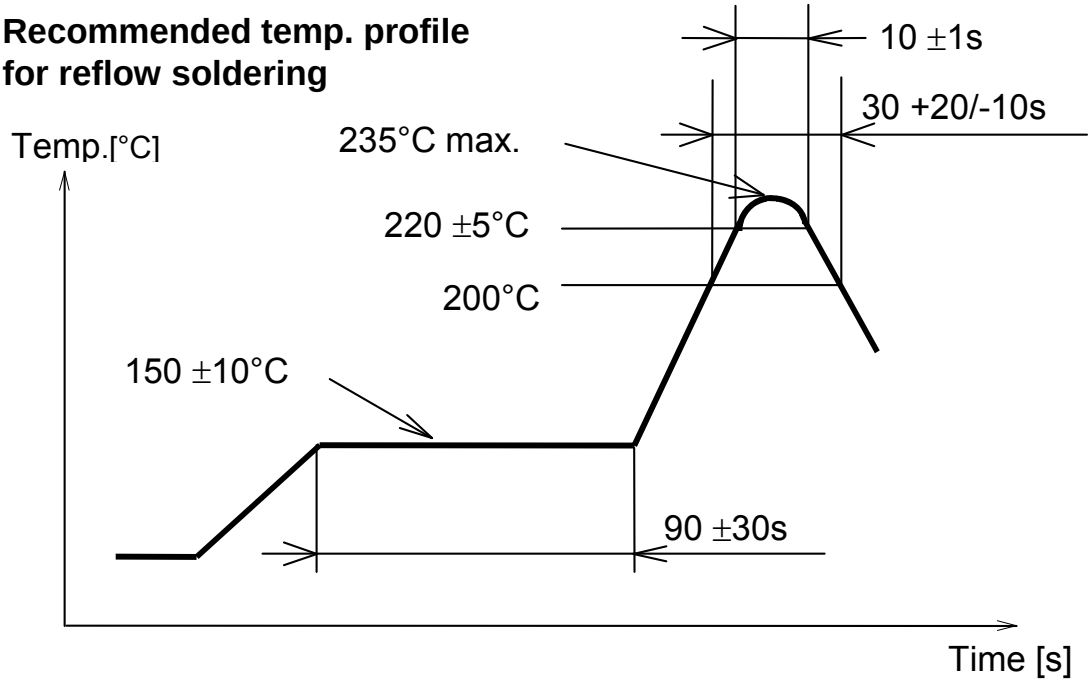
No	Characteristics	Condition	Min	Typ	Max	BT Spec	Unit
1	Operation frequency range		2402		2480		MHz
2	Channel spacing			2			MHz
3	Output Power	Maximum setting, measured at single ended 50ohm.		4			dBm
		Minimum setting, measured at single ended 50ohm.		-24			dBm
4	Sensitivity, High Gain Mode	High-gain mode		-93.0		-70	dBm
		Standard mode		-92.5		-70	

No	Characteristics	Condition	Typ	Max	Unit
1	Spurious emissions	Conducted measurement with a 50-Ω single-ended load. Complies with EN 300 328, EN 300 440 class 2, FCC CFR47, Part 15 and ARIB STD-T-66		-41	dBm

13. SOLDERING TEMPERATURE-TIME PROFILE (FOR REFLOW SOLDERING)

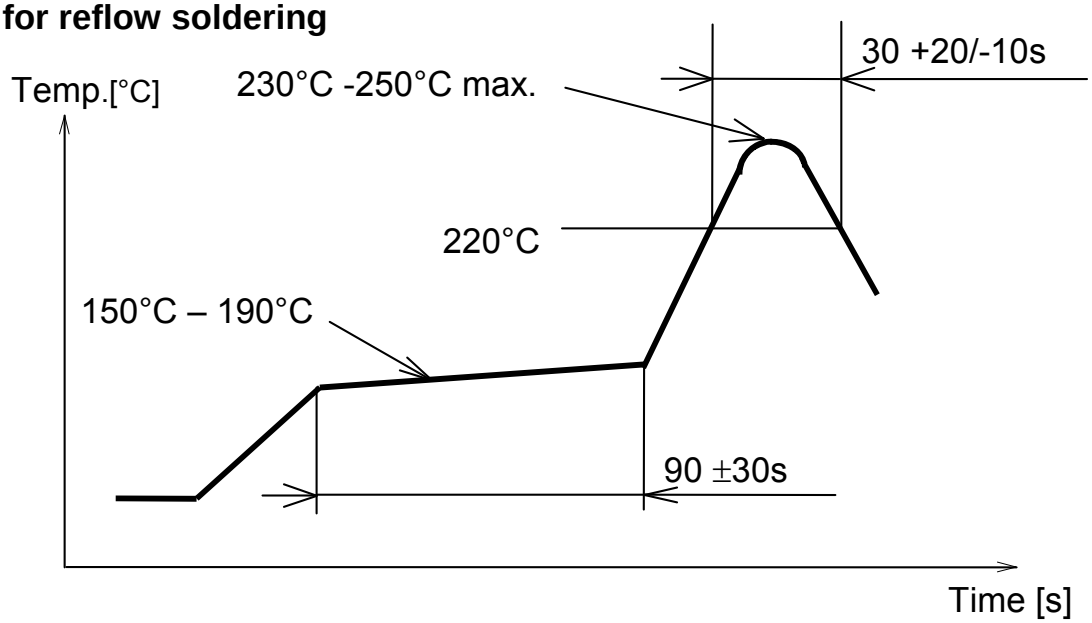
13.1. FOR LEAD SOLDER

Recommended temp. profile for reflow soldering



13.2. FOR LEADFREE SOLDER

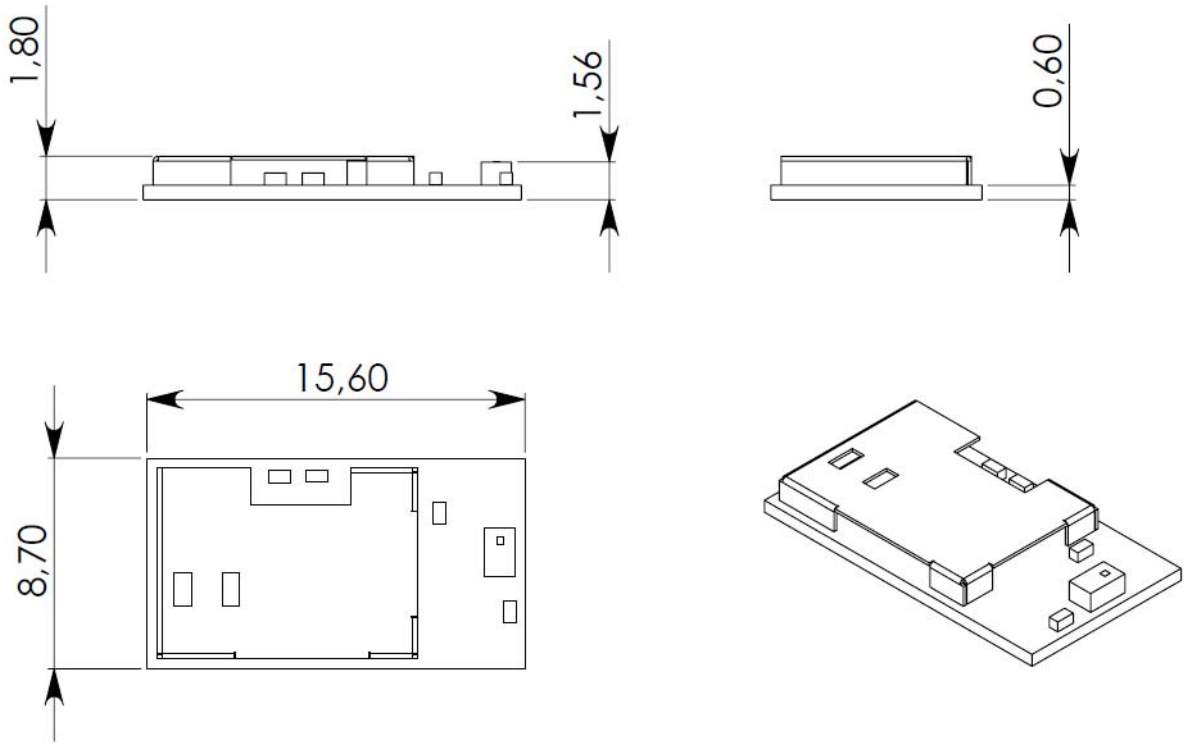
Our used temp. profile for reflow soldering



Reflow permissible cycle: 2
Opposite side reflow is prohibited due to module weight.

14. MODULE DIMENSION

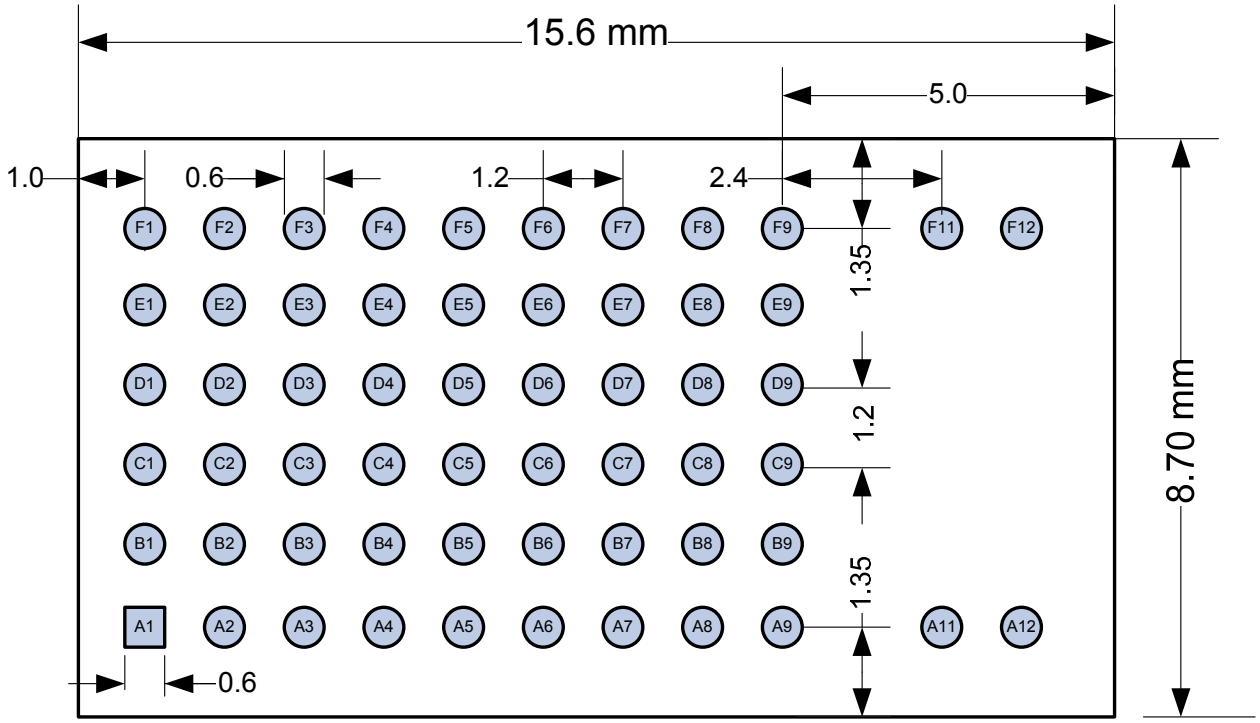
No.	Item	Dimension	Tolerance	Remark
1	Width	8.70	± 0.20	
2	Length	15.60	± 0.20	
3	Height	1.80	± 0.20	With case



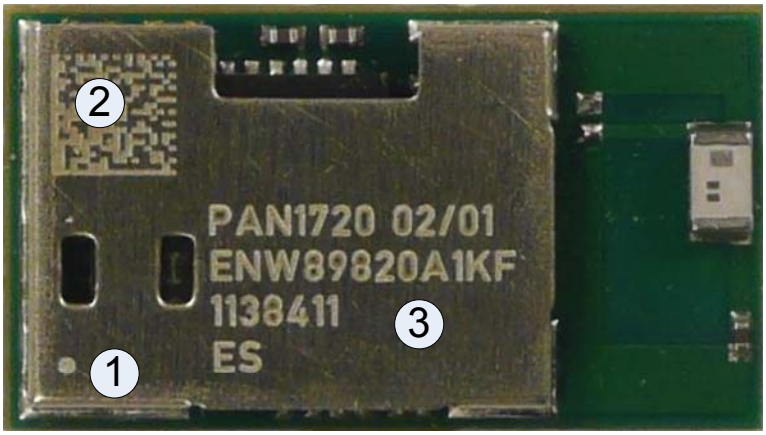
15. PAN172X FOOTPRINT OF THE MODULE

All dimensions are in millimeters.
The outer dimensions have a tolerance of ± 0.2mm.

Top view, Application PCB



16. CASE MARKING



No.	Remark
1	Marking for Pin 1 (Circle 0,15 mm)
2	2D-Code, for internal usage only and can be change without any notice
3	Marking definition see chapter 15.1

16.1. EXAMPLE FOR MARKING

P	A	N	1	7	2	0			H	W	/	S	W			
E	N	W	8	9	8	2	0	A	x	K	F					
Y	Y	W	W	D	L	L										
F	C	C	I	D	:		T	7	V	P	A	N	1	7		

16.2. MARKING DEFINITION

(1) Pin1 marking

(2) 2D code (Serial number)

(3) Marking:

- PAN172x (Model Name), HW/SW (Hardware/Software version)
- ENW89820AxKF (Part Number, refer to chapter 22 Ordering Information)
- Lot code (YearYear, WeekWeek, Day, LotLot)
- ES (Engineering Sample marking)

Note: For available Software Versions, refer to PAN172xETU Design-Guide 0 and chapter 22 Ordering Information.

17. MECHANICAL REQUIREMENTS

No.	Item	Limit	Condition
1	Solderability	More than 75% of the soldering area shall be coated by solder	Reflow soldering with recommendable temperature profile
2	Resistance to soldering heat	It shall be satisfied electrical requirements and not be mechanical damage	See chapter 13.2

18. DEVELOPMENT OF APPLICATIONS

For development support please refer to PAN172xETU Design-Guide

http://www.pedeu.panasonic.de/pdf/168ApplicationNote.pdf 0.

19. RELIABILITY TESTS

The measurement should be done after being exposed to room temperature and humidity for 1 hour.

No.	Item	Limit	Condition
1	Vibration test	Electrical parameter should be in specification	a) Freq.:10~50Hz,Amplitude:1.5mm a) 20min. / cycle,1hrs. each of XYZ axis b) Freq.:30~100Hz, 6G b) 20min. / cycle,1hrs. each of XYZ axis
2	Shock test	the same as above	Dropped onto hard wood from height of 50cm for 3 times
3	Heat cycle test	the same as above	-40°C for 30min. and +85°C for 30min.; each temperature 300 cycles
4	Moisture test	the same as above	+60°C, 90% RH, 300h
5	Low temp. test	the same as above	-40°C, 300h
6	High temp. test	the same as above	+85°C, 300h

20. CAUTIONS

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

20.1. DESIGN NOTES

(1) Follow the conditions written in this specification, especially the control signals of this module.
(2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).
(3) This product should not be mechanically stressed when installed.
(4) Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
(5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.

(6) The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.
(7) Keep this product away from other high frequency circuits.

20.2. INSTALLATION NOTES

(1) Reflow soldering is possible twice based on the conditions in chapter 15. Set up the temperature at the soldering portion of this product according to this reflow profile.
(2) Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
(3) Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
(4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
(5) This product should not be mechanically stressed or vibrated when reflowed.
(6) If you want to repair your board by hand soldering, please keep the conditions of this chapter.
(7) Do not wash this product.
(8) Refer to the recommended pattern when designing a board.
(9) Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.
(10) For more details on LGA (Land Grid Arrey) soldering processes refer to the application note.

20.3. USAGE CONDITIONS NOTES

(1) Take measures to protect the unit against static electricity.
If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation befor assembly on the final products.
(2) Do not use dropped products.
(3) Do not touch, damage or soil the pins.
(4) Follow the recommended condition ratings about the power supply applied to this product.
(5) Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB.
(6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.
(7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

20.4. STORAGE NOTES

(1) The module should not be stressed mechanically during storage.
(2) Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:
- Storage in salty air or in an environment with a high concentration of corrosive gas, such as Cl2, H2S, NH3, SO2, or NOX
- Storage in direct sunlight
- Storage in an environment where the temperature may be outside the range of 5°C to 35°C range, or where the humidity may be outside the 45 to 85% range.
- Storage of the products for more than one year after the date of delivery Storage period: Please check the adhesive strength of the embossed tape and soldering after 6 months of storage.

(3) Keep this product away from water, poisonous gas and corrosive gas.
(4) This product should not be stressed or shocked when transported.
(5) Follow the specification when stacking packed crates (max. 10).

20.5. SAFETY CAUTIONS

These specifications are intended to preserve the quality assurance of products and individual components.

Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

(1) Ensure the safety of the whole system by installing a protection circuit and a protection device.
(2) Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a single fault causing an unsafe status.

20.6. OTHER CAUTIONS

(1) This specification sheet is copyrighted. Please do not disclose it to a third party.
(2) Please do not use the products for other purposes than those listed.
(3) Be sure to provide an appropriate fail-safe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.
(4) This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
(5) These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.

- In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
- In direct sunlight, outdoors, or in a dusty environment
- In an environment where condensation occurs.
- In an environment with a high concentration of harmful gas (e.g. salty air, HCl, Cl2, SO2, H2S, NH3, and NOX)

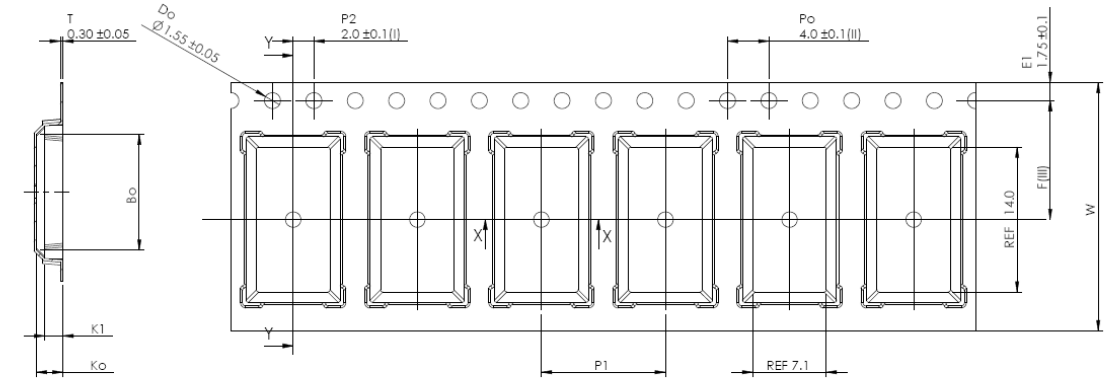
(6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.

(7) When you have any question or uncertainty, contact Panasonic.

21. PACKAGING

If the product has mass production status, indicated in chapter 0, we will deliver the module in the package which are described below.

21.1. TAPE DIMENSION



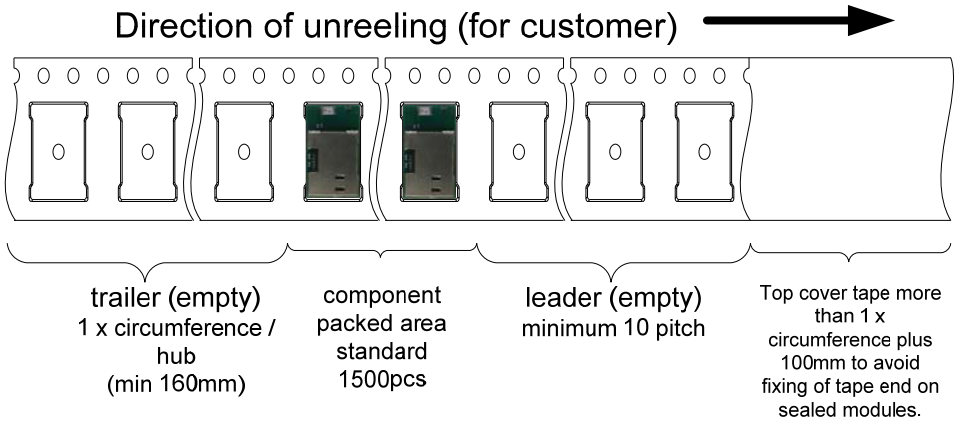
A o	9.10	+/- 0.1
B o	16.00	+/- 0.1
K o	3.20	+/- 0.1
K 1	2.20	+/- 0.1
F	11.50	+/- 0.1
P 1	12.00	+/- 0.1
W	24.00	+/- 0.3

Forming format : Flatbed
Estimated max. length : 64 meter/22B3 reel

(I) Measured from centreline of sprocket hole to centreline of pocket.
(II) Cumulative tolerance of 10 sprocket holes is ±0.20 .
(III) Measured from centreline of sprocket hole to centreline of pocket.
(IV) Other material available.

ALL DIMENSIONS IN MILLIMETRES UNLESS OTHERWISE STATED.

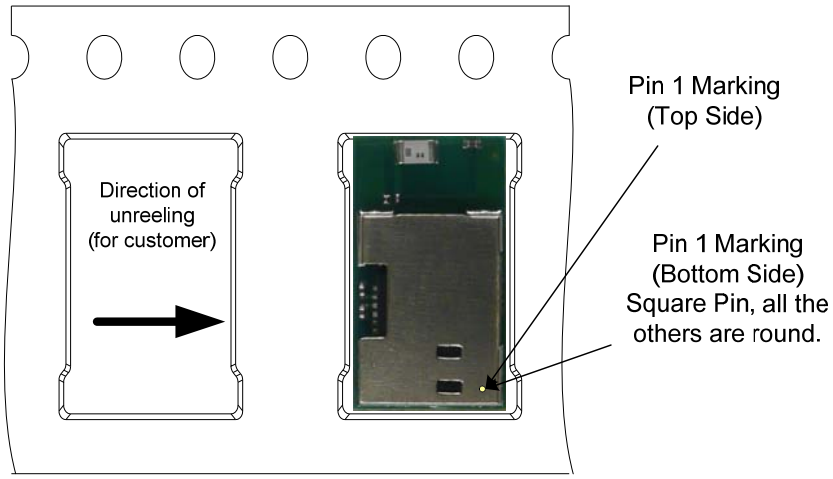
21.2. PACKING IN TAPE



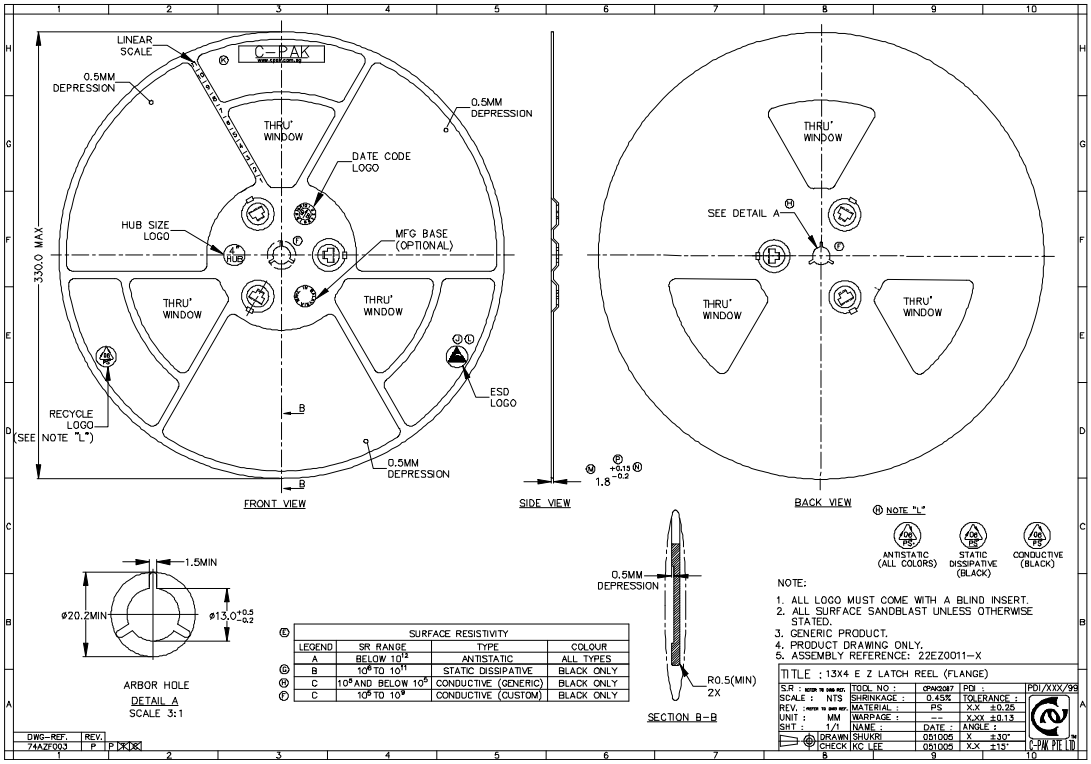
Empty spaces in component packed area shall be less than two per reel and those spaces shall not be consecutive.

Top cover tape shall not be found on reel holes and shall not stick out from reel.

21.3. COMPONENT DIRECTION



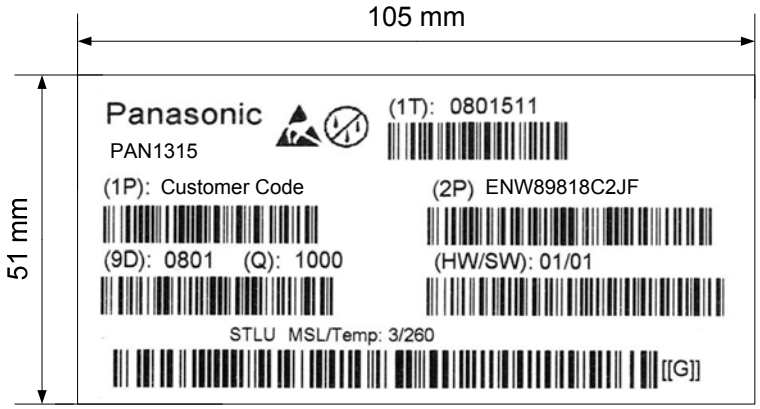
21.4. REEL DIMENSION



SURFACE RESISTIVITY			
LEGEND	SR RANGE	TYPE	COLOUR
A	BELOW 10^{12}	ANTISTATIC	ALL TYPES
B	10^{6} TO 10^{11}	STATIC DISSIPATIVE	BLACK ONLY
C	10^{5} AND BELOW 10^{6}	CONDUCTIVE (GENERIC)	BLACK ONLY
C	10^{5} TO 10^{9}	CONDUCTIVE (CUSTOM)	BLACK ONLY

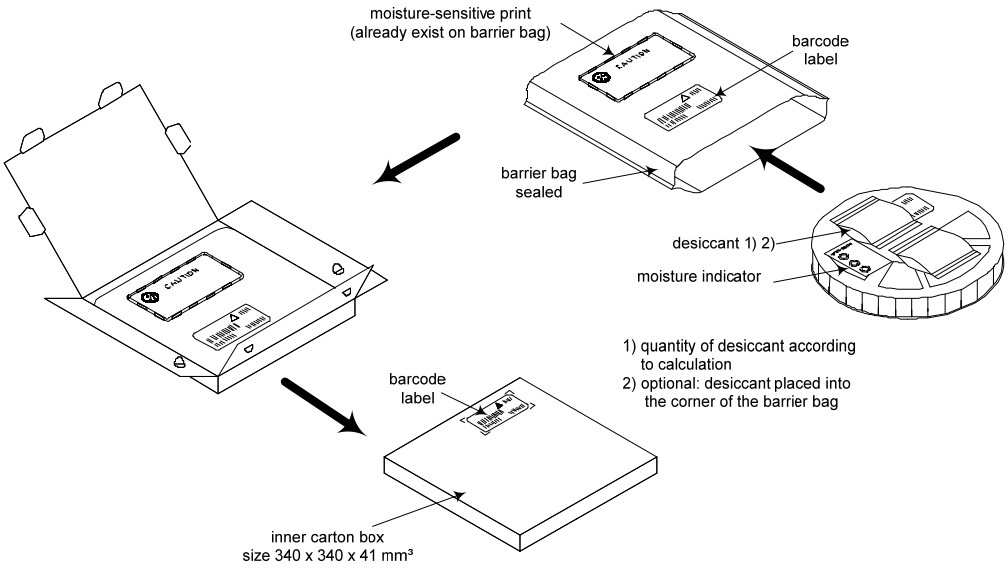
21.5. LABEL FOR PACKAGE

The picture shows an example from similar product.



(1T)	Lot code [YYWWDLL]		Example from above:
	YY	year	printed 08
	WW	normal calendar week	printed 01
	D	day	printed 5 (Friday)
	L	line identifier, if more as one	printed 1
	L	lot identifier per day	printed 1
(1P)	Customer Order Code, if any, otherwise company name will be printed		
(2P)	Panasonic Order Code: ENW89820AxKF		
(9D)	Date code as [YYWW]		
(Q)	Quantity [XXXX], variable max. 1500		
(HW/SW)	Hardware /Software Release		
	Hardware 01	Indicates the HW revision.	
	Software 01	Indicates the SW revision.	

21.6. TOTAL PACKAGE



22. ORDERING INFORMATION

Ordering part number	Description	MOQ (1)
ENW89820A1KF (2)	PAN1720 CLASS 2 Bluetooth single mode Module according BT-4.0. *Bluetooth*® smart device	1500
ENW89820A3KF (2)	PAN1720 Same as above including BlueRadios BR-SPP FW version. *Bluetooth*® smart device	1500
ENW89835A1KF (2)	PAN1721 CLASS 2 Bluetooth single mode Module according BT-4.0. *Bluetooth*® smart device	1500
ENW89835A3KF (2)	PAN1721 Same as above including BlueRadios BR-SPP FW version. *Bluetooth*® smart device	1500

Notes:

(1) Abbreviation for Minimum Order Quantity (MOQ). The standard MOQ for mass production is 1500 pieces, fewer only on customer demand. Samples for evaluation can be delivered at any quantity via the distribution channels.

(2) Samples are available on customer demand

22.1. INFORMATION REGARDING SOFTWARE VERSIONS

ENW89820A1KF:

The modules will be delivered with an empty flash. Customers need to program their own TI software in the production process. For details refer to the design guide.

ENW89820A3KF:

The modules are delivered with BlueRadios nBlue software. This software includes a bootloader and can be updated over the UART. For the latest revision refer to this link: http://blueradios.com/panasonic/index.php

Note: New customers seeking firmware and firmware support are required to register by providing an invoice number.

23. ROHS DECLARATION

Declaration of environmental compatibility for supplied products:

Hereby we declare to our best present knowledge based on declaration of our suppliers that this product do not contain by now the following substances which are banned by Directive 2002/95/EC (RoHS) or if contain a maximum concentration of 0,1% by weight in homogeneous materials for

- Lead and lead compounds
- Mercury and mercury compounds
- Chromium (VI)
- PBB (polybrominated biphenyl) category
- PBDE (polybrominated biphenyl ether) category

And a maximum concentration of 0,01% by weight in homogeneous materials for

- Cadmium and cadmium compounds

24. DATA SHEET STATUS

Panasonic reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Please consult the most recently issued data sheet before initiating or completing a design.

Use this URL to search for the most recent version of this data sheet: Use this URL to search for the most recent version of this data sheet:

PAN172x Datasheet

25. HISTORY FOR THIS DOCUMENT

Revision	Date	Modification / Remarks
0.01	November 2011	1st preliminary version.
0.02	November 2011	Deleted footnote in chapter 11.
1.00	April 2012	Released Version.
1.1	July 2012	Add chapter 22.1 Information regarding Software Versions. Link to LGA app note. Removed watermark. UART pinning for BR-SW version. I2C pinning for PAN1721 version. FCC, IC, IDs.
1.2	July 2012	Added remark "top view" for footprint. Corrected FCC ID to T7VPAN17.

26. RELATED DOCUMENTS

For an update, please search in the suitable homepage.

PAN172xETU Design-Guide

http://www.pedeu.panasonic.de/pdf/168ApplicationNote.pdf

Semiconductor Datasheet

CC2540 from Texas Instruments

CC2541 from Texas Instruments

Application Note Land Grid Array

http://www.pedeu.panasonic.de/pdf/184ext.pdf

27. GENERAL INFORMATION

© Panasonic Industrial Devices Europe GmbH 2012.
All rights reserved.
This product description does not lodge the claim to be complete and free of mistakes.
Please contact the related product manager in every case.

If we deliver ES samples to the customer, these samples have the status Engineering Samples. This means, the design of this product is not yet concluded. Engineering Samples may be partially or fully functional, and there may be differences to be published Data Sheet.
Engineering Samples are not qualified and are not to be used for reliability testing or series production.

Disclaimer:
Customer acknowledges that samples may deviate from the Data Sheet and may bear defects due to their status of development and the lack of qualification mentioned above.
Panasonic rejects any liability or product warranty for Engineering Samples. In particular, Panasonic disclaims liability for damages caused by

- the use of the Engineering Sample other than for Evaluation Purposes, particularly the installation or integration in an other product to be sold by Customer,
- deviation or lapse in function of Engineering Sample,
- improper use of Engineering Samples.

Panasonic disclaimes any liability for consequential and incidental damages.
In case of any questions, please contact your local sales partner or the related product manager.

28. REGULATORY INFORMATION

28.1. FCC NOTICE

The devices PAN17, for details refer to Chapter 22, including the antennas, which are listed in 28.5, complies with Part 15 of the FCC Rules. The device meets the requirements for modular transmitter approval as detailed in FCC public Notice DA00-1407.transmitter
Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

28.2. CAUTION

The FCC requires the user to be notified that any changes or modifications made to this device that are not expressly approved by Panasonic Industrial Devices Europe GmbH may void the user's authority to operate the equipment.
This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a

particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help

28.3. LABELING REQUIREMENTS

The Original Equipment Manufacturer (OEM) must ensure that FCC labeling requirements are met. This includes a clearly visible label on the outside of the OEM enclosure specifying the appropriate Panasonic FCC identifier for this product as well as the FCC Notice above. The FCC identifier are **FCC ID: T7VPAN17**. This FCC identifier is valid for all PAN172x modules, for details, see the Chapter 22. Ordering Information.

In any case the end product must be labelled exterior with "Contains FCC ID: T7VPAN17"

28.4. ANTENNA WARNING

For the related part number of PAN172x refer to Chapter 22. Ordering Information.

This devices are tested with a standard SMA connector and with the antennas listed below. When integrated in the OEMs product, these fixed antennas require installation preventing end-users from replacing them with non-approved antennas. Any antenna not in the following table must be tested to comply with FCC Section 15.203 for unique antenna connectors and Section 15.247 for emissions. The FCC identifier for this device with the antenna listed in item 1 are the same (FCC ID: T7VPAN17).

28.5. APPROVED ANTENNA LIST

Note: We are able to qualify your antenna and will add to this list as that process is completed.

Item	Part Number	Manufacturer	Frequency Band	Type	Gain (dBi)
2	LDA212G3110K	Murata	2.4GHz	Chip-Antenna	+0.9

28.6. RF EXPOSURE PAN172X

To comply with FCC RF Exposure requirements, the Original Equipment Manufacturer (OEM) must ensure that the approved antenna in the previous table must be installed.

The preceding statement must be included as a CAUTION statement in manuals for products operating with the approved antennas in the previous table to alert users on FCC RF Exposure compliance.

Any notification to the end user of installation or removal instructions about the integrated radio module is not allowed.

The radiated output power of PAN172x with mounted ceramic antenna **(FCC ID: T7VPAN17)** is far below the FCC radio frequency exposure limits. Nevertheless, the PAN172x shall be used in such a manner that the potential for human contact during normal operation is minimized.

End users may not be provided with the module installation instructions. OEM integrators and end users must be provided with transmitter operating conditions for satisfying RF exposure compliance.

29. INDUSTRY CANADA CERTIFICATION

PAN172x is licensed to meet the regulatory requirements of Industry Canada (IC),

license: IC: 216Q-PAN17

Manufacturers of mobile, fixed or portable devices incorporating this module are advised to clarify any regulatory questions and ensure compliance for SAR and/or RF exposure limits. Users can obtain Canadian information on RF exposure and compliance from www.ic.gc.ca.

This device has been designed to operate with the antennas listed in Table 20 above, having a maximum gain of 0.9 dBi. Antennas not included in this list or having a gain greater than 0.9 dBi are strictly prohibited for use with this device. The required antenna impedance is 50 ohms. The antenna used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

Due to the model size the IC identifier is displayed in the installation instruction only and can not be displayed on the modules label due to the limited size (8.7x15.6mm).

29.1. IC NOTICE

The devices PAN172x, for details refer to Chapter 22, including the antennas, which are listed in 28.5, complies with Canada RSS-GEN Rules. The device meets the requirements for modular transmitter approval as detailed in RSS-GEN. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

29.2. LABELING REQUIREMENTS

The Original Equipment Manufacturer (OEM) must ensure that IC labeling requirements are met. This includes a clearly visible label on the outside of the OEM enclosure specifying the appropriate Panasonic IC identifier for this product as well as the IC Notice above. The IC identifier is 216Q-PAN17. This IC identifier is valid for all PAN172x modules, for details, see the Chapter 22. Ordering Information.

In any case the end product must be labelled exterior with "Contains IC: 216Q-PAN17"

30. EUROPEAN R&TTE DECLARATION OF CONFORMITY

Hereby, Panasonic Industrial Devices Europe GmbH, declares that the Bluetooth module PAN172x and their versions is in compliance with the essential requirements and other relevant provisions of Directive 1999/5/EC. As a result of the conformity assessment procedure described in Annex III of the Directive 1999/5/EC, the end-customer equipment should be labelled as follows:

CE

PAN172x and their versions in the specified reference design can be used in the following countries: Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, The Netherlands, the United Kingdom, Switzerland, and Norway.

31. LIFE SUPPORT POLICY

This Panasonic product is not designed for use in life support appliances, devices, or systems where malfunction can reasonably be expected to result in a significant personal injury to the user, or as a critical component in any life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness. Panasonic customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panasonic for any damages resulting.